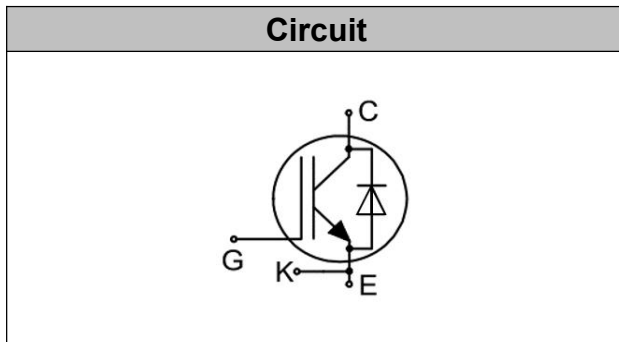


IGBT Discrete

V_{CE}	1200	V
I_C	40	A
$V_{CE(SAT)} I_C=40A$	1.65	V
P_D	320	W

Top View

Bottom View



Applications

- Inverter for motor drive
- AC and DC servo drive amplifier
- PTC heater

Features

- High breakdown voltage to 1200V for improved reliability
- Maximum junction temperature 175°C
- Positive temperature coefficient
- Including fast & soft recovery anti-parallel FWD
- High short circuit capability(10us)
- Qualified to AEC-Q101

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-Emitter Breakdown Voltage	V_{CE}	1200	V
DC Collector Current, limited by T_{jmax} $T_C=25^{\circ}C$ $T_C=100^{\circ}C$	I_C	80 40	A
Diode Forward Current, limited by T_{jmax} $T_C=25^{\circ}C$ $T_C=100^{\circ}C$	I_F	80 40	A
Continuous Gate-Emitter Voltage	V_{GE}	± 20	V
Transient Gate-Emitter Voltage ($t_p \leq 10\mu s, D < 0.010$)	V_{GE}	± 30	V
Turn off Safe Operating Area $V_{CE} \leq 1200V$, $T_j \leq 150^{\circ}C$		160	A
Pulsed Collector Current, $V_{GE}=15V$, t_p limited by T_{jmax}	I_{CM}	160	A
Diode Pulsed Current, t_p limited by T_{jmax}	I_{Fpuls}	160	A
Short Circuit Withstand Time, $V_{GE}=15V, V_{CC}=600V, V_{CEM} \leq 1200V$	T_{sc}	10	μs
Power Dissipation, $T_j=175^{\circ}C, T_C=25^{\circ}C$	P_{tot}	320	W



Operating Junction Temperature	T_j	-40...+175	°C
Storage Temperature	T_s	-55...+150	°C
Soldering Temperature, wave soldering 1.6mm (0.063in.) from case for 10s		260	°C

Electrical Characteristics of the IGBT ($T_j=25^\circ\text{C}$ unless otherwise specified):

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static						
Collector-Emitter Breakdown Voltage	BV_{CES}	$V_{GE}=0V, I_C=250\mu A$	1200		-	V
Gate Threshold Voltage	$V_{GE(th)}$	$V_{GE}=V_{CE}, I_C=1.0mA$	5.2	5.8	6.5	V
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$V_{GE}=15V, I_C=40A$ $T_j=25^\circ\text{C}$, $T_j=125^\circ\text{C}$ $T_j=150^\circ\text{C}$		1.65 1.95 2.05	1.95	V
Zero Gate Voltage Collector Current	I_{CES}	$V_{CE}=1200V, V_{GE}=0V$ $T_j=25^\circ\text{C}$, $T_j=150^\circ\text{C}$			0.25 4	mA
Gate-Emitter Leakage Current	I_{GES}	$V_{CE}=0V, V_{GE}=\pm 20V$			100	nA

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Dynamic						
Input Capacitance	C_{ies}	$V_{CE}=25V, V_{GE}=0V,$ $f=1\text{MHz}$	-	6.76	-	nF
Output Capacitance	C_{oes}		-	0.19	-	
Reverse Transfer Capacitance	C_{res}		-	0.07	-	
Gate Charge	Q_G	$V_{CC}=600V, I_C=40A,$ $V_{GE}=15V$	-	0.27	-	uC

**Electrical Characteristics of the Diode** ($T_j = 25^\circ\text{C}$ unless otherwise specified):

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static						
Diode Forward Voltage	V_F	$I_F = 40\text{A}$ $T_j = 25^\circ\text{C}$, $T_j = 125^\circ\text{C}$ $T_j = 150^\circ\text{C}$		2.40 2.30 2.20	3.00	V

Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Dynamic , at $T_j = 25^\circ\text{C}$						
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{CC} = 600\text{V}$, $I_C = 40\text{A}$, $V_{GE} = -5\text{V} \sim 15\text{V}$, $R_g = 20\Omega$	-	93	-	ns
Rise Time	t_r		-	80	-	ns
Turn-on Energy	E_{on}		-	3.13	-	mJ
Turn-off Delay Time	$t_{d(\text{off})}$		-	269	-	ns
Fall Time	t_f		-	171	-	ns
Turn-off Energy	E_{off}		-	2.05	-	mJ
Dynamic , at $T_j = 125^\circ\text{C}$						
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{CC} = 600\text{V}$, $I_C = 40\text{A}$, $V_{GE} = -5\text{V} \sim 15\text{V}$, $R_g = 20\Omega$	-	87	-	ns
Rise Time	t_r		-	83	-	ns
Turn-on Energy	E_{on}		-	3.46	-	mJ
Turn-off Delay Time	$t_{d(\text{off})}$		-	288	-	ns
Fall Time	t_f		-	249	-	ns
Turn-off Energy	E_{off}		-	2.69	-	mJ
Dynamic , at $T_j = 150^\circ\text{C}$						
Turn-on Delay Time	$t_{d(\text{on})}$	$V_{CC} = 600\text{V}$, $I_C = 40\text{A}$, $V_{GE} = -5\text{V} \sim 15\text{V}$, $R_g = 20\Omega$	-	84	-	ns
Rise Time	t_r		-	86	-	ns
Turn-on Energy	E_{on}		-	3.56	-	mJ
Turn-off Delay Time	$t_{d(\text{off})}$		-	300	-	ns
Fall Time	t_f		-	282	-	ns
Turn-off Energy	E_{off}		-	2.90	-	mJ

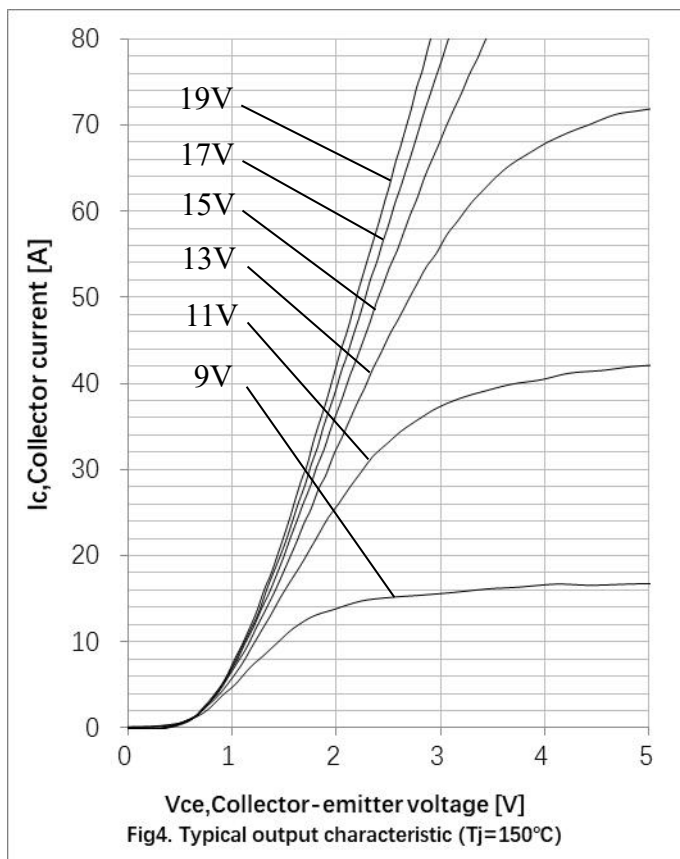
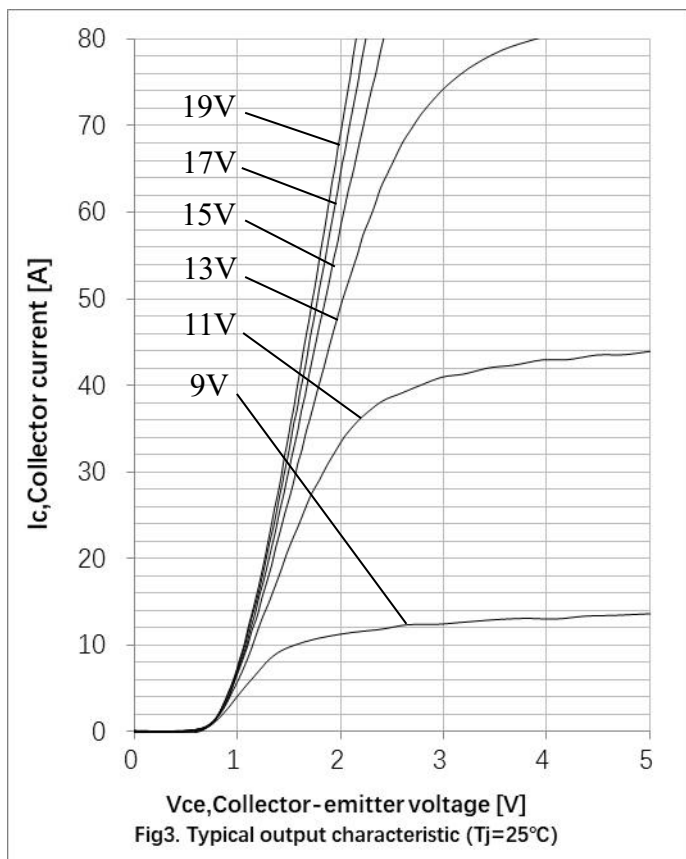
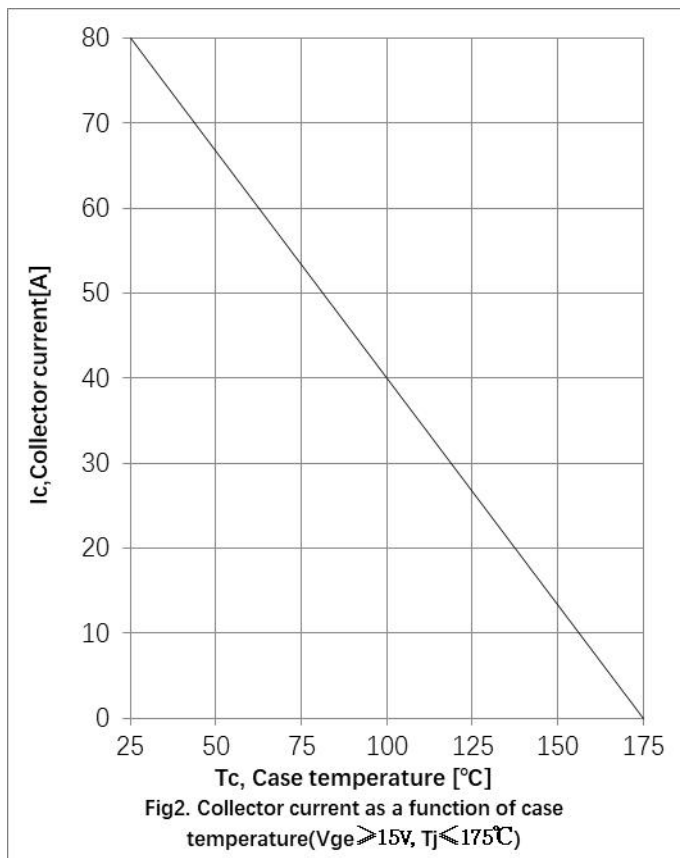
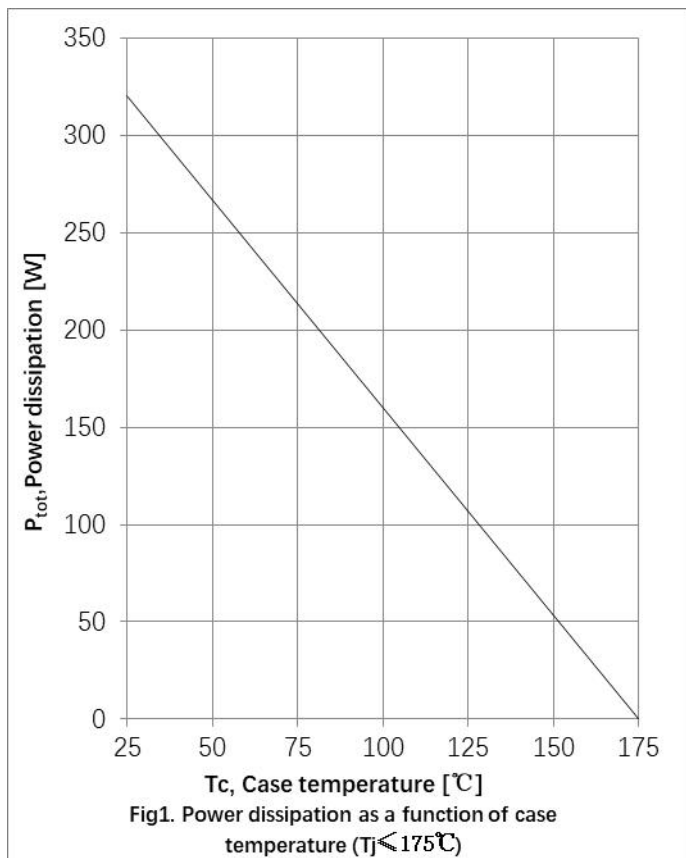


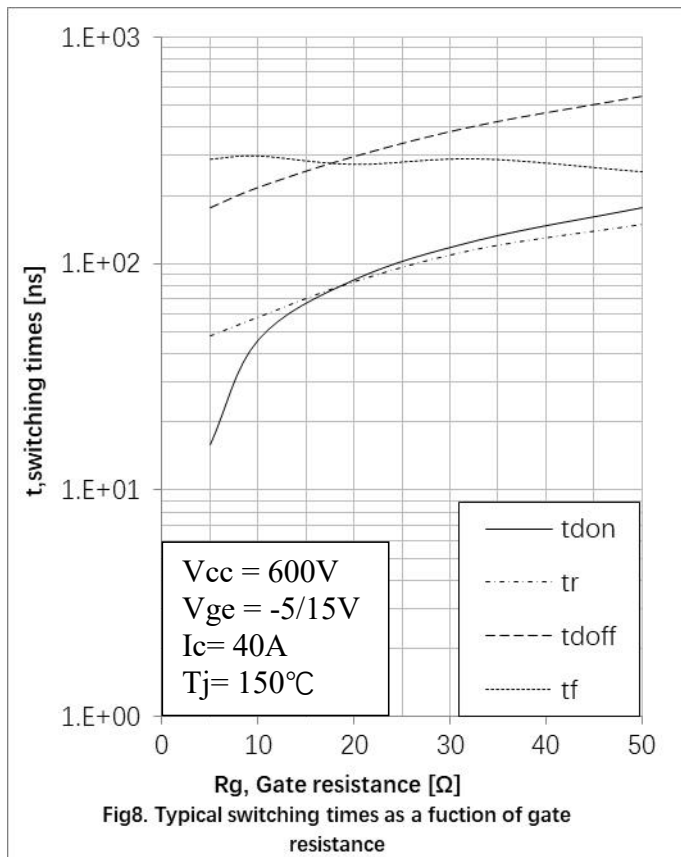
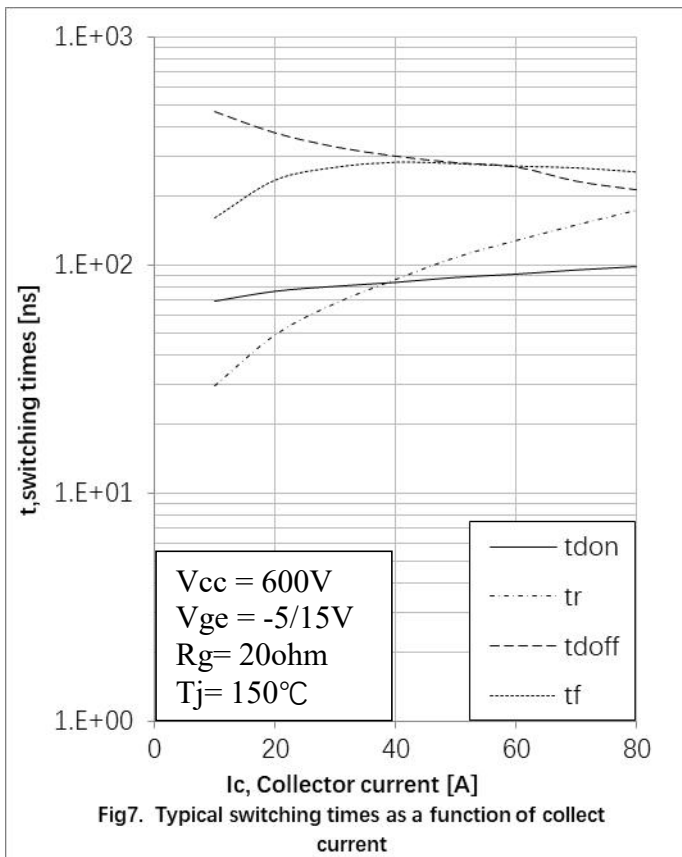
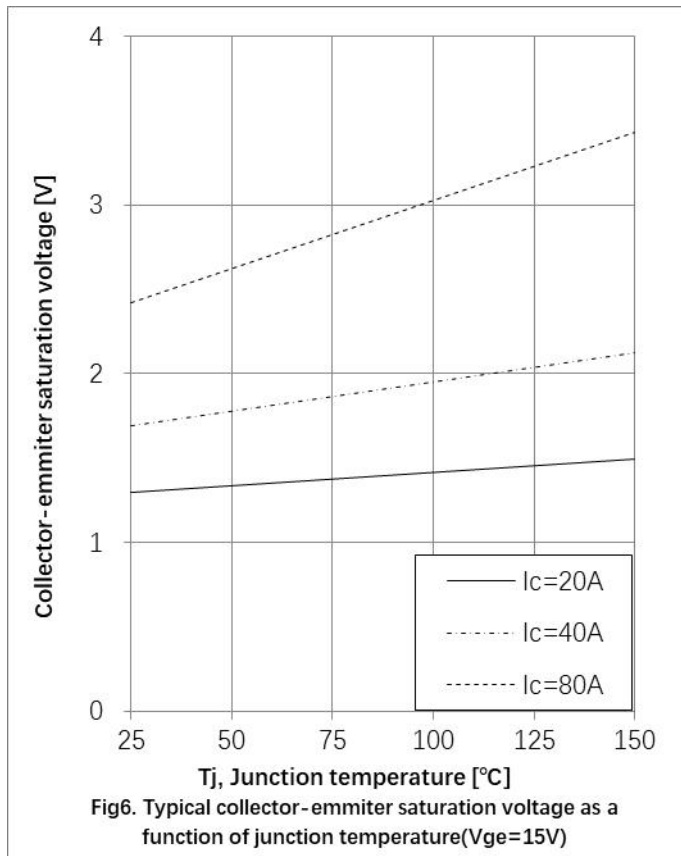
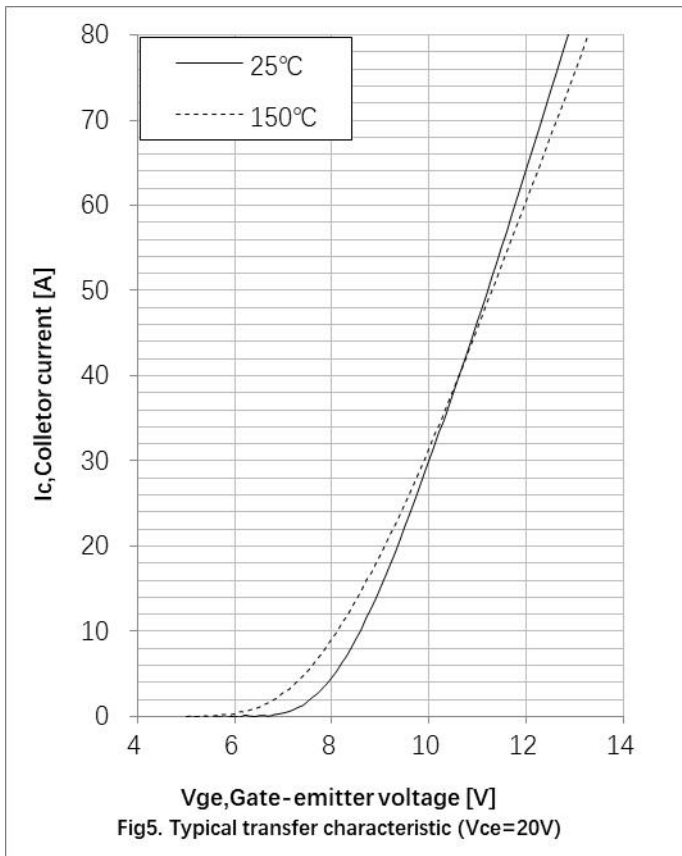
Electrical Characteristics of the DIODE

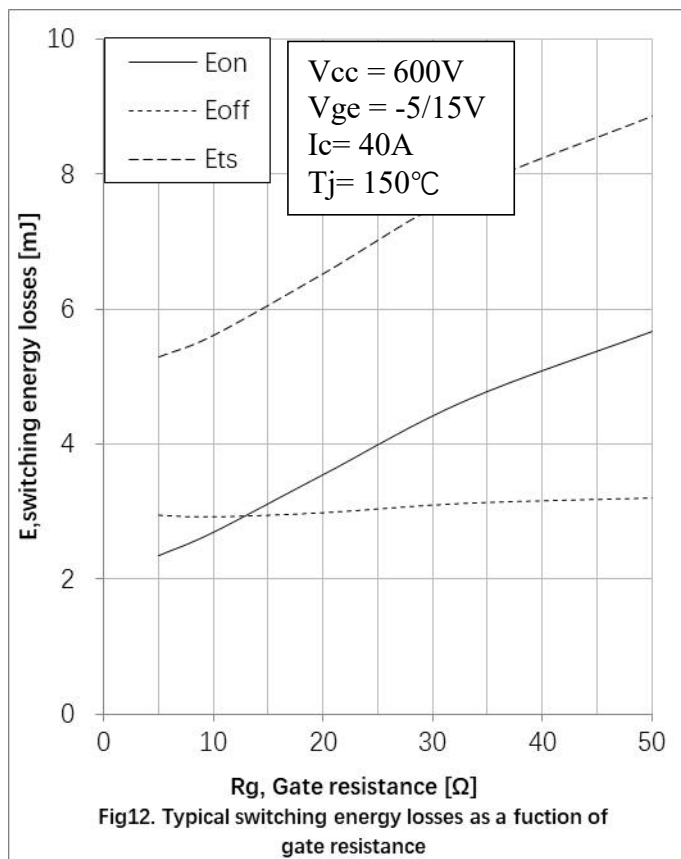
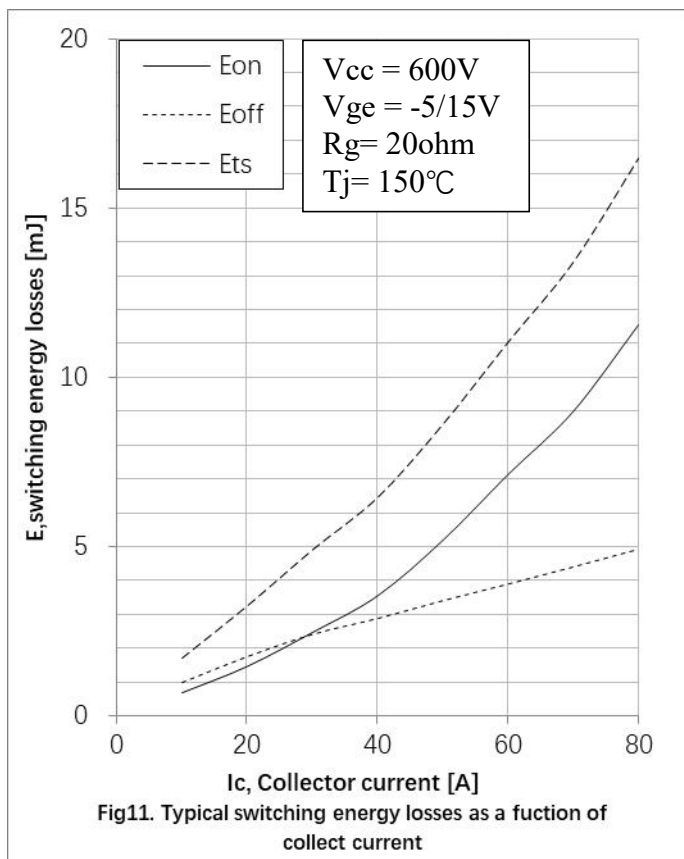
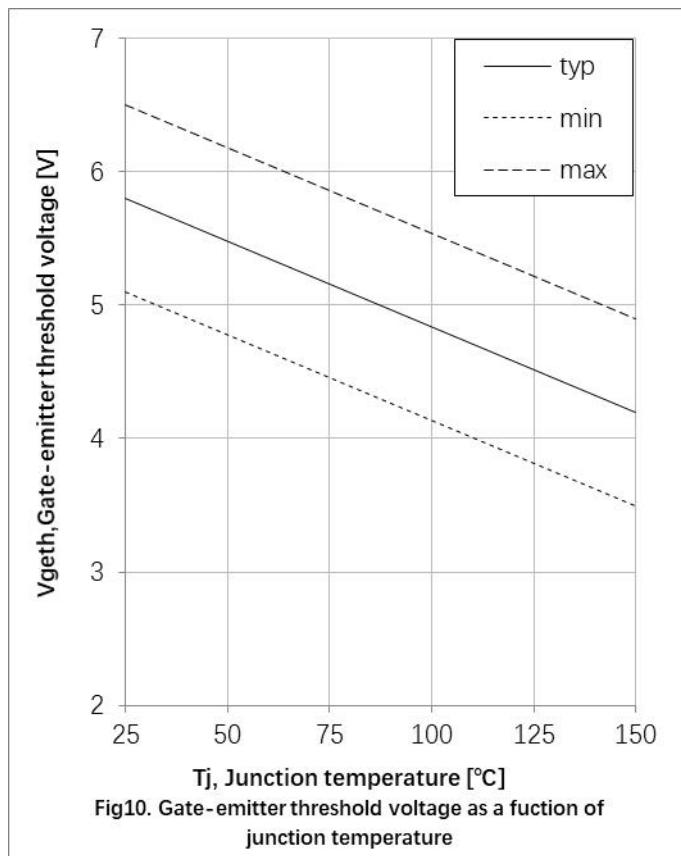
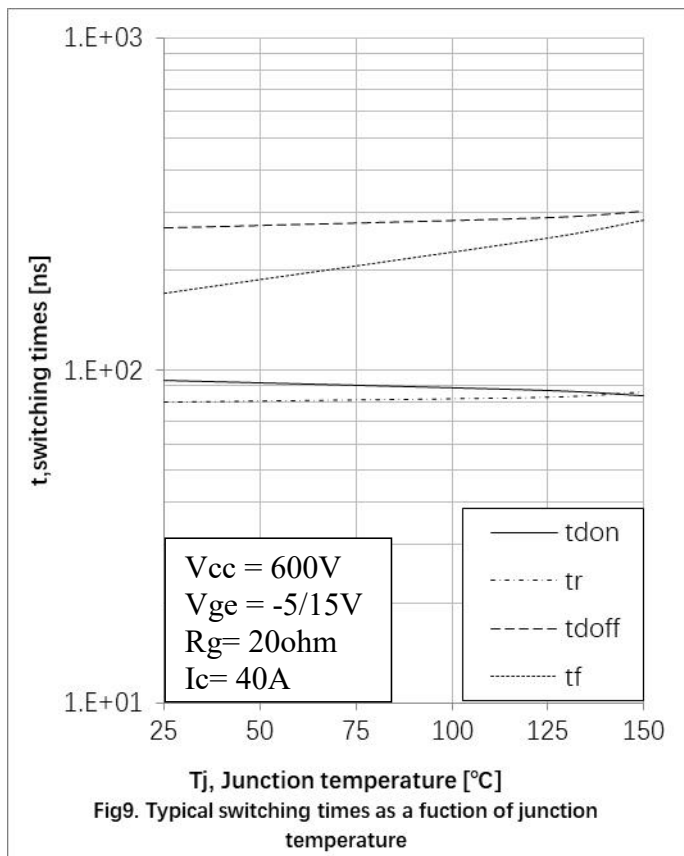
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Dynamic , at T_j= 25°C						
Reverse Recovery Current	I _{rr}	I _F =40A, V _R =600V, di/dt= -350A/μs,	-	40	-	A
Diode reverse recovery time	t _{rr}		-	215	-	ns
Reverse Recovery Charge	Q _{rr}		-	1.22	-	uC
Reverse Recovery Energy	E _{rec}		-	0.43	-	mJ
Dynamic , at T_j= 125°C						
Reverse Recovery Current	I _{rr}	I _F =40A, V _R =600V di/dt= -350A/μs,	-	41	-	A
Diode reverse recovery time	t _{rr}		-	317	-	ns
Reverse Recovery Charge	Q _{rr}		-	2.64	-	uC
Reverse Recovery Energy	E _{rec}		-	1.05	-	mJ
Dynamic , at T_j= 150°C						
Reverse Recovery Current	I _{rr}	I _F =40A, V _R =600V di/dt= -350A/μs,	-	42	-	A
Diode reverse recovery time	t _{rr}		-	369	-	ns
Reverse Recovery Charge	Q _{rr}		-	3.44	-	uC
Reverse Recovery Energy	E _{rec}		-	1.34	-	mJ

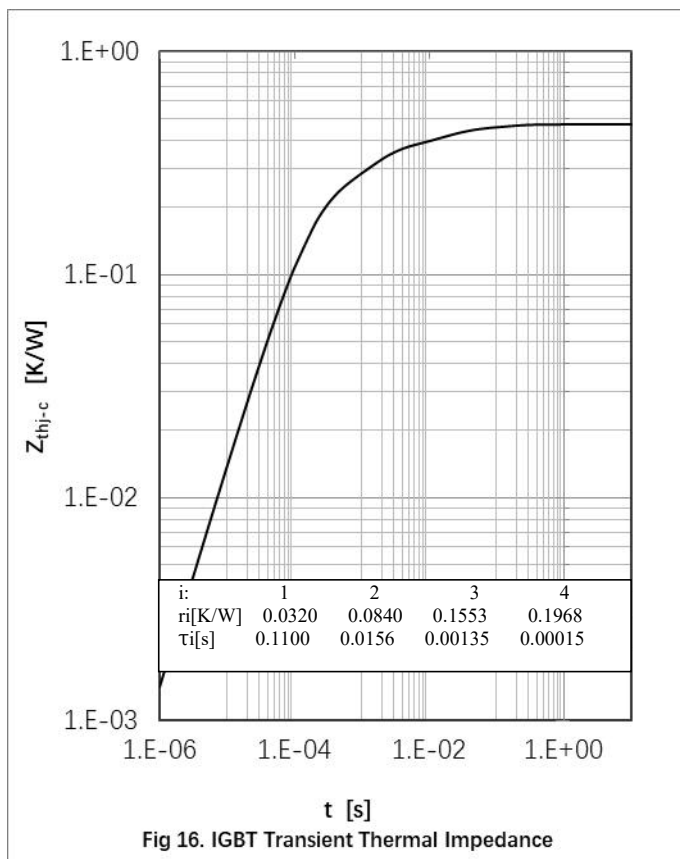
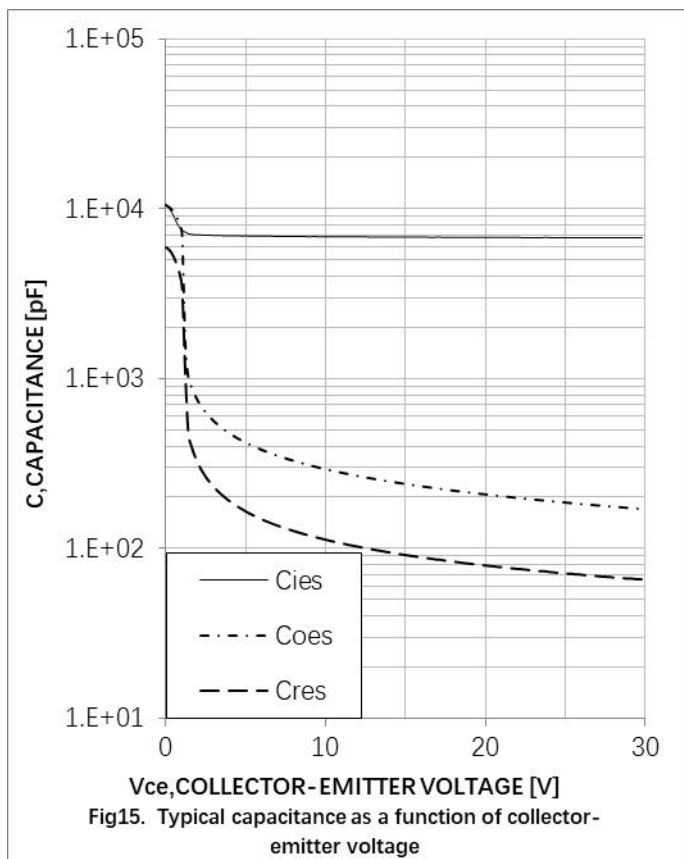
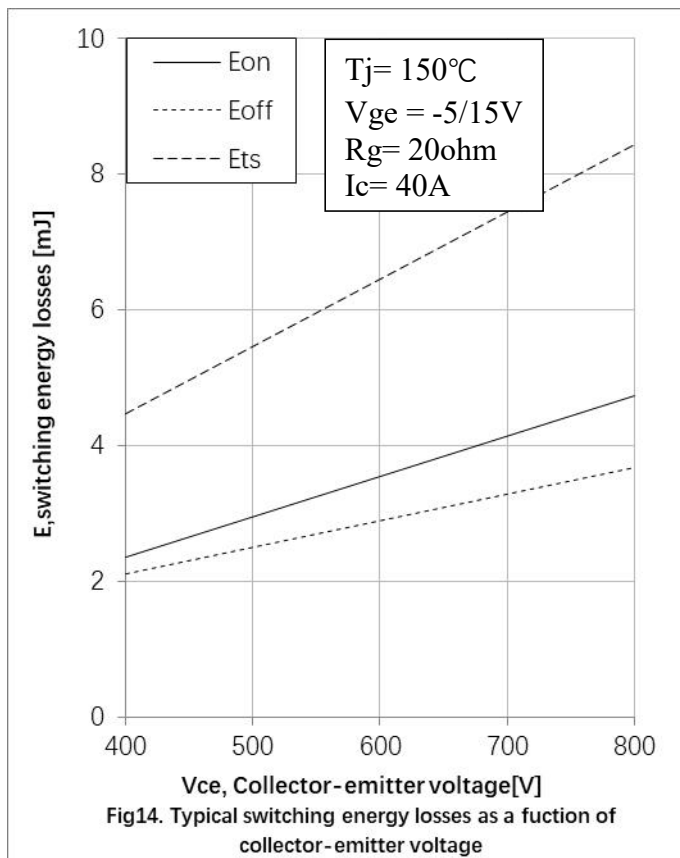
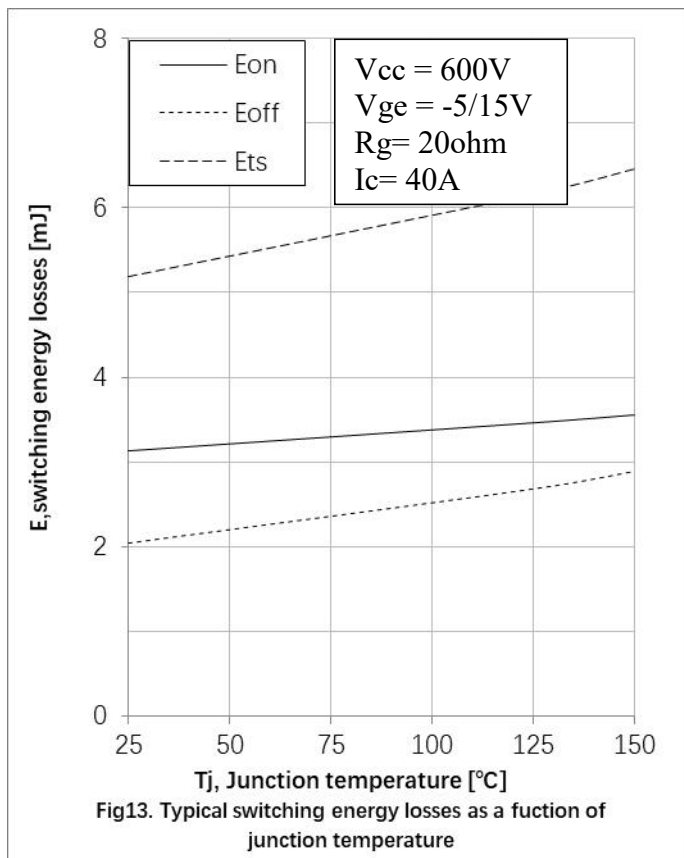
Thermal Resistance

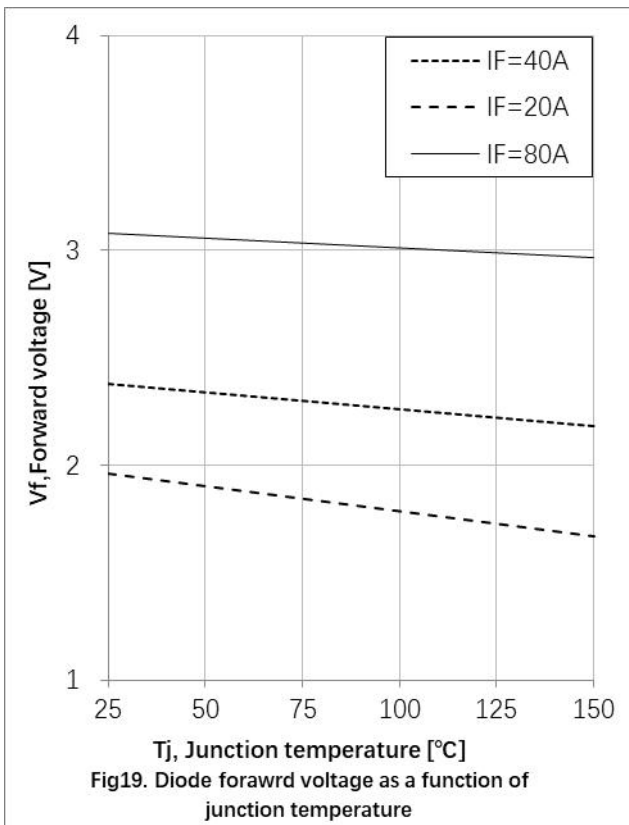
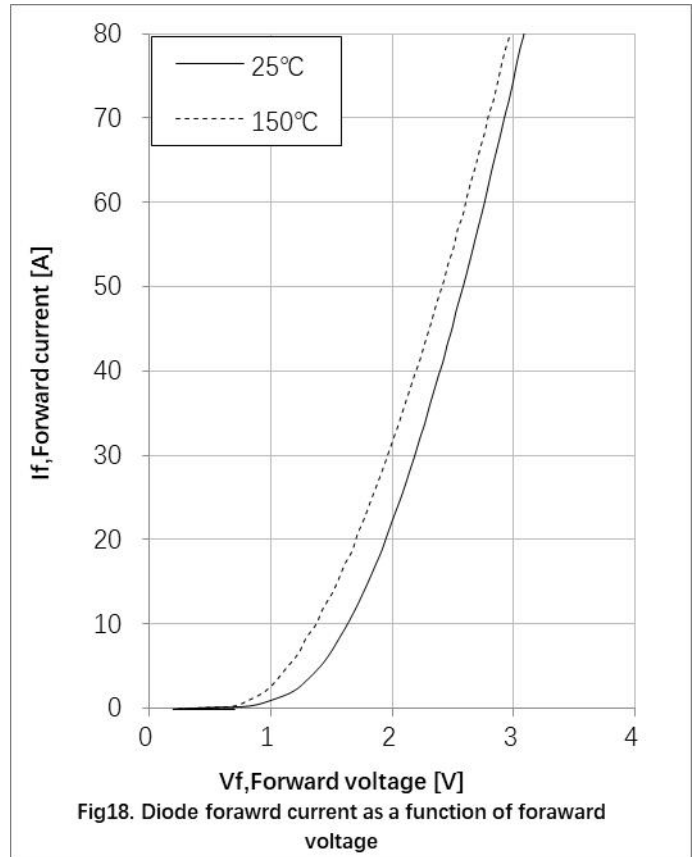
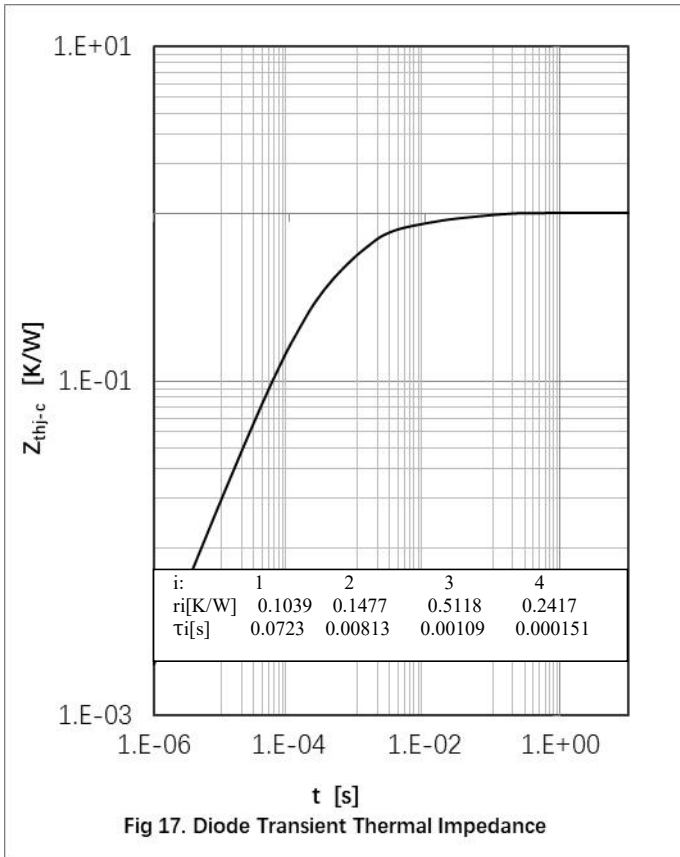
Parameter	Symbol	Max. Value	Unit
IGBT Thermal Resistance, Junction - Case	R _{θ(j-c)}	0.47	K/W
Diode Thermal Resistance, Junction - Case	R _{θ(j-c)}	1.00	K/W
Thermal Resistance, Junction - Ambient	R _{θ(j-a)}	40	K/W





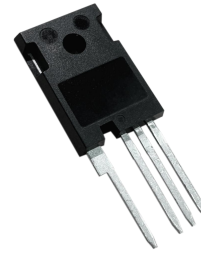
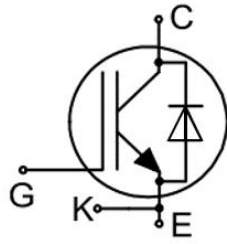






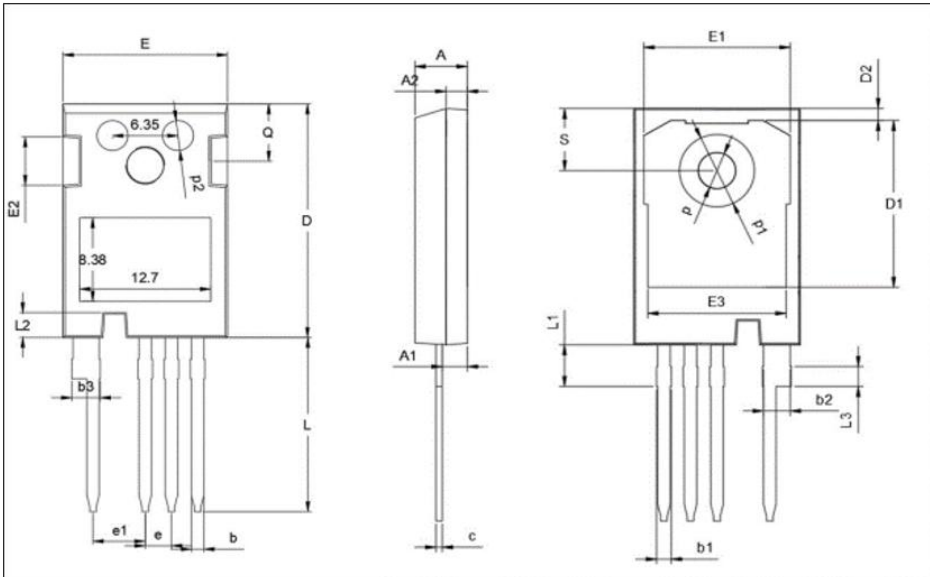


● **Circuit Diagram**



● **Package Outline Information**

CASE: TO 247-4L



TO247-4L			
Dim	Min	Norm	Max
A	4.80	5.00	5.20
A1	2.30	2.40	2.50
A2	1.88	1.98	2.08
b	1.10	1.20	1.30
b1	1.20	/	1.50
b2	2.35	2.55	2.75
b3	2.45	/	2.85
c	0.55	0.60	0.65
D	23.3	23.45	23.6
D1	16.25	16.55	16.85
D2	1.00	/	1.30
e	TYP2.54		
e1	TYP5.06		
E	15.75	15.90	16.05
E1	13.80	/	14.20
E2	4.40	4.75	5.10
E3	13.00	/	13.45
L	17.34	17.49	17.64
L1	4.00	/	4.30
L2	2.35	/	2.65
L3	TYP1.98		
Q	5.60	5.80	6.00
S	6.05	/	6.30
p	TYP3.58		
p1	TYP7.18		
p2	TYP3.00		



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